

28cl

Docket No. 0039-7292-2 DIV

IN RE APPLICATION OF: KAORI UMEZAWA, ET AL.

SERIAL NO: 09/358,388

FILED: JULY 21, 1999

FOR: SUBSTRATE HAVING SHALLOW TRENCH ISOLATION AND METHOD OF MANUFACTURING THE SAME

*RESPONSE UNDER 37 CFR 1.116-
EXPEDITED PROCEDURE EXAMINING
GROUP 2814

ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

SIR:

Transmitted herewith is an amendment in the above-identified application.

- ☒ No additional fee is required
- ☐ Small entity status of this application under 37 C.F.R. §1.9 and §1.27 has been established by a verified statement previously submitted.
- ☐ Small entity status of this application under 37 C.F.R. §1.9 and §1.27 has been established by a verified statement submitted herewith.
- ☒ Additional documents filed herewith: LETTER REQUESTING APPROVAL OF DRAWING CHANGES MARKED IN RED WITH 1 ATTACHMENT

The Fee has been calculated as shown below:

CLAIMS	CLAIMS REMAINING		HIGHEST NUMBER PREVIOUSLY PAID	NO. EXTRA CLAIMS	RATE	CALCULATIONS
TOTAL	19	MINUS	20	0	× \$18 =	\$0.00
INDEPENDENT	8	MINUS	8	0	× \$80 =	\$0.00
		<input type="checkbox"/> MULTIPLE DEPENDENT CLAIMS			+ \$270 =	\$0.00
		TOTAL OF ABOVE CALCULATIONS				\$0.00
		<input type="checkbox"/> Reduction by 50% for filing by Small Entity				\$0.00
		<input type="checkbox"/> Recordation of Assignment			+ \$40 =	\$0.00
		TOTAL				\$0.00

- ☐ A check in the amount of \$_____ is attached.
- ☒ Please charge any additional Fees for the papers being filed herewith and for which no check is enclosed herewith, or credit any overpayment to deposit Account No. 15-0030. A duplicate copy of this sheet is enclosed.
- ☒ If these papers are not considered timely filed by the Patent and Trademark Office, then a petition is hereby made under 37 C.F.R. §1.136, and any additional fees required under 37 C.F.R. §1.136 for any necessary extension of time may be charged to Deposit Account No. 15-0030. A duplicate copy of this sheet is enclosed.



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0039-7292-2 DIV

91C
RESPONSE UNDER 37 CFR 1.116-
EXPEDITED PROCEDURE EXAMINING
GROUP 2814

~~(A.E.)~~
Lewis
10/20/00

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF:

KAORI UMEZAWA ET AL.

: GROUP ART UNIT: 2814

SERIAL NO: 09/358,388

FILED: JULY 21, 1999

: EXAMINER: MAI, A.

Enter
Marsha
11/28/00

FOR: SUBSTRATE HAVING SHALLOW :
TRENCH ISOLATION AND
METHOD OF MANUFACTURING
THE SAME

AMENDMENT UNDER 37 CFR §1.116

ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

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SIR:

In response to the outstanding Action mailed July 19, 2000, please amend the above-identified application as follows:

IN THE CLAIMS

✓
✓
✓
Please amend Claims 9 and 25-29 as follows:

Subs
C'
--9. (Twice Amended) A method of manufacturing a semiconductor substrate having shallow trench isolation regions and device regions sandwiched by the shallow trench isolation regions, comprising the steps of:

(a) a first step of forming a plurality of grooves on part of a surface of the semiconductor substrate;

(b) a second step of depositing oxide films in the grooves by an organic silicon based CVD method and then removing upper parts of the oxide films so as to planarize a surface of